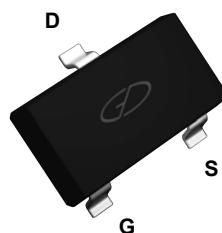
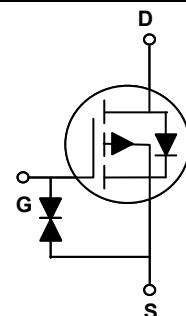


## Main Product Characteristics

BV <sub>DSS</sub>	-20V
R <sub>DS(ON)</sub> @V <sub>GS</sub> =-4.5V	640mΩ
I <sub>D</sub>	-0.85A



SOT-323



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSFC1208 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V <sub>DS</sub>	-20	V
Gate-Source Voltage	V <sub>GS</sub>	±8	V
Drain Current-Continuous (T <sub>A</sub> =25°C) <sup>1,3</sup>	I <sub>D</sub>	-0.85	A
Drain Current-Continuous (T <sub>A</sub> =70°C) <sup>1,3</sup>		-0.68	
Drain Current-Pulsed <sup>2</sup>	I <sub>DM</sub>	-2.1	A
Power Dissipation (T <sub>A</sub> =25°C)	P <sub>D</sub>	0.69	W
Power Dissipation (T <sub>A</sub> =70°C)		0.44	W
Thermal Resistance, Junction-to-Ambient <sup>1</sup>	R <sub>θJA</sub>	180	°C/W
Operating Junction Temperature Range	T <sub>J</sub>	-55 To +150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 To +150	°C

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-20	-	-	V
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=-16\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 12\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 10$	$\mu\text{A}$
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-0.55\text{A}$	-	530	640	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}, I_{\text{D}}=-0.45\text{A}$		730	950	
		$V_{\text{GS}}=-1.8\text{V}, I_{\text{D}}=-0.35\text{A}$	-	1300	1950	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=-250\mu\text{A}$	-0.5	-	-1	V
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-0.55\text{A}$	-	1	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-1\text{A}$ $V_{\text{GS}}=-2.5\text{V}$	-	0.53	-	nC
Total Gate Charge	$Q_g$	$V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-1\text{A}$ $V_{\text{GS}}=-4.5\text{V}$	-	0.8	-	
Gate-Source Charge	$Q_{\text{gs}}$		-	0.2	-	
Gate-Drain Charge	$Q_{\text{gd}}$		-	0.2	-	
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DS}}=-10\text{V}, R_{\text{G}}=3\Omega$ $V_{\text{GS}}=-4.5\text{V},$ $I_{\text{D}}=-1.33\text{A}$	-	400	-	nS
Rise Time	$t_r$		-	60	-	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	20	-	
Fall Time	$t_f$		-	800	-	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=-10\text{V}, V_{\text{GS}}=0\text{V},$ $F=1\text{MHz}$	-	58	-	pF
Output Capacitance	$C_{\text{oss}}$		-	5.7	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	4.4	-	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{SD}}=-1\text{A}$	-	-	-1.1	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_{\text{F}}=-1\text{A}$ $dI/dt=100\text{A}/\mu\text{s}$	-	9.2	-	nS
Reverse Recovery Charge	$Q_{\text{rr}}$		-	0.8	-	nC

Note:

- The value of  $R_{\text{eJA}}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any given application depends on the user's specific board design.
- Repetitive Rating: pulse width limited by maximum junction temperature.
- The current rating is based on the t<10s junction to ambient thermal resistance rating.

## Typical Electrical and Thermal Characteristic Curves

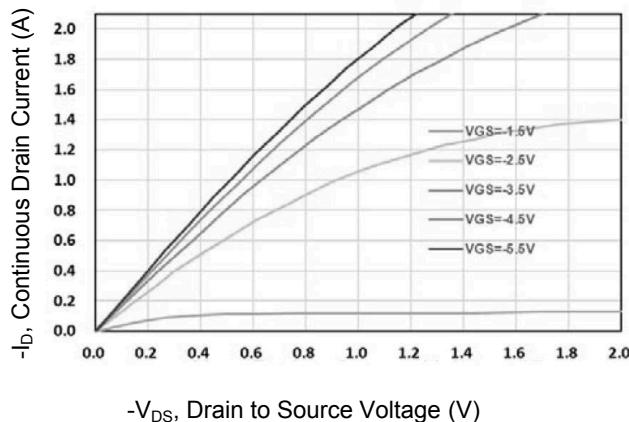


Figure 1. Typical Output Characteristics

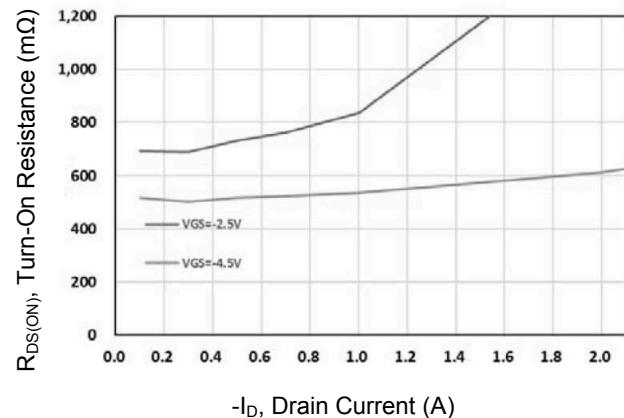


Figure 2. Turn-On Resistance vs.  $I_D$

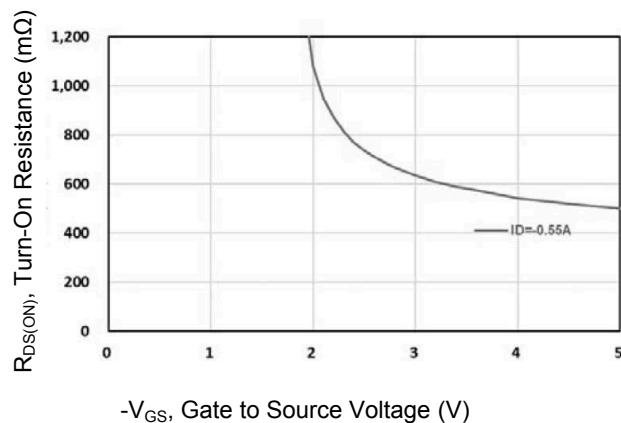


Figure 3. Turn-On Resistance vs.  $V_{GS}$

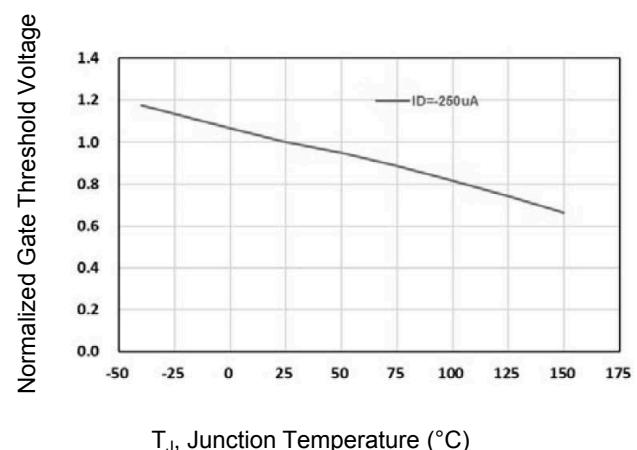


Figure 4. Normalized  $V_{th}$  vs.  $T_J$

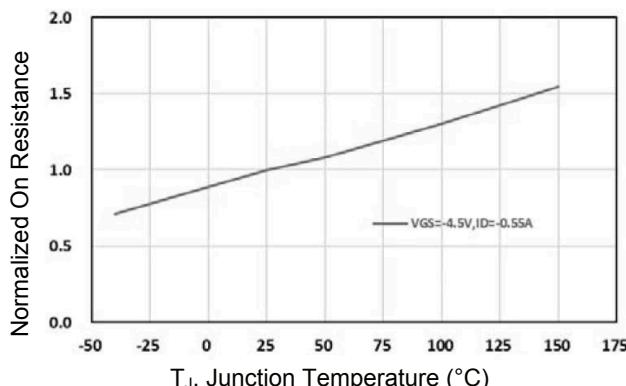


Figure 5. Normalized  $R_{DS(on)}$  vs.  $T_J$

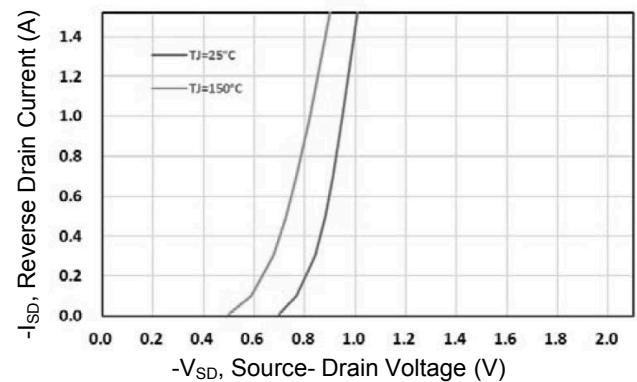


Figure 6. Typical Source-Drain Diode Forward Voltage

## Typical Electrical and Thermal Characteristic Curves

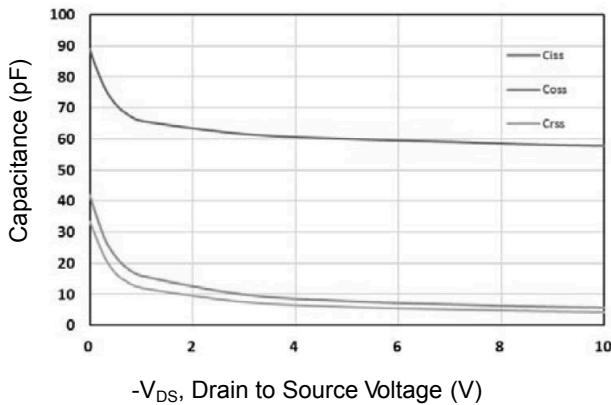


Figure 7. Capacitance Characteristics

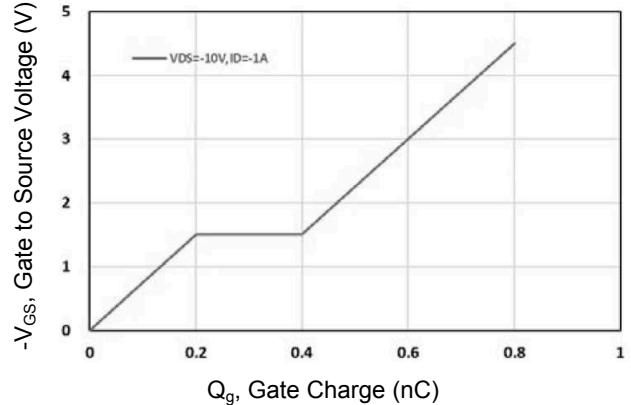


Figure 8. Gate Charge Characteristics

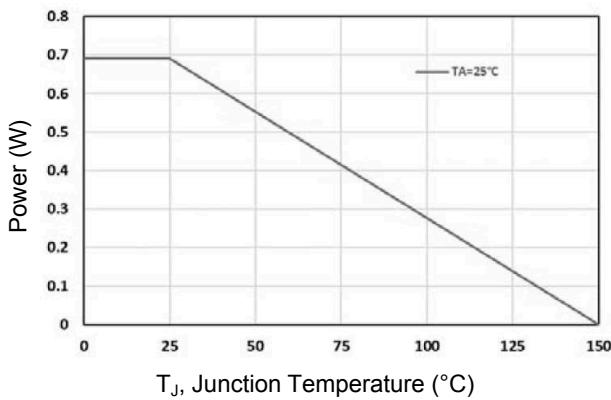


Figure 9. Power Dissipation

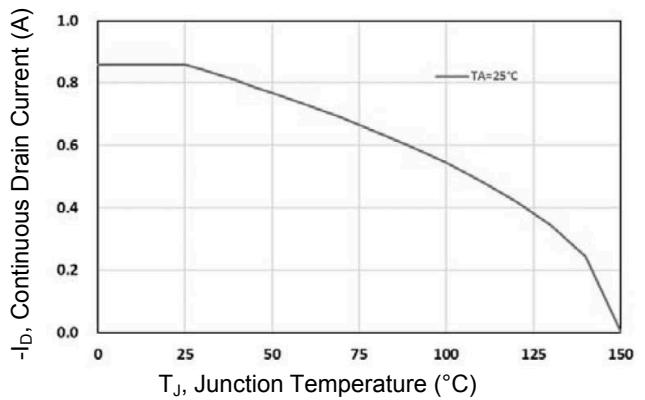


Figure 10. Drain Current

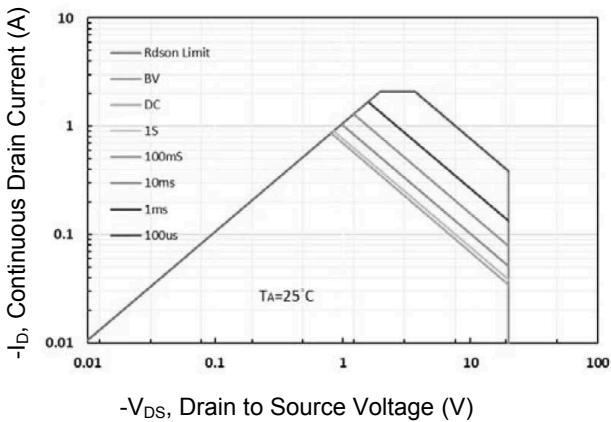


Figure 11. Maximum Safe Operation Area

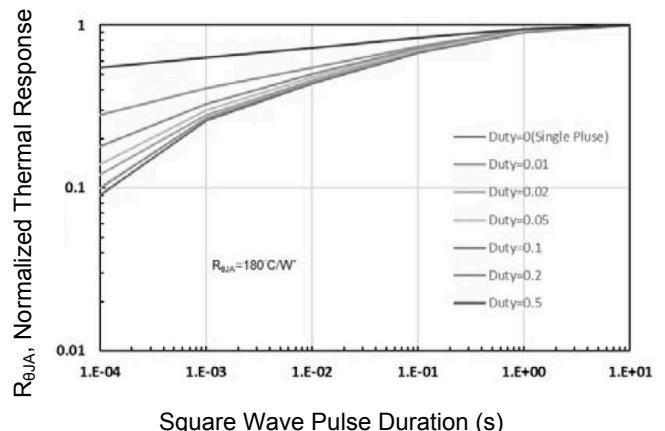
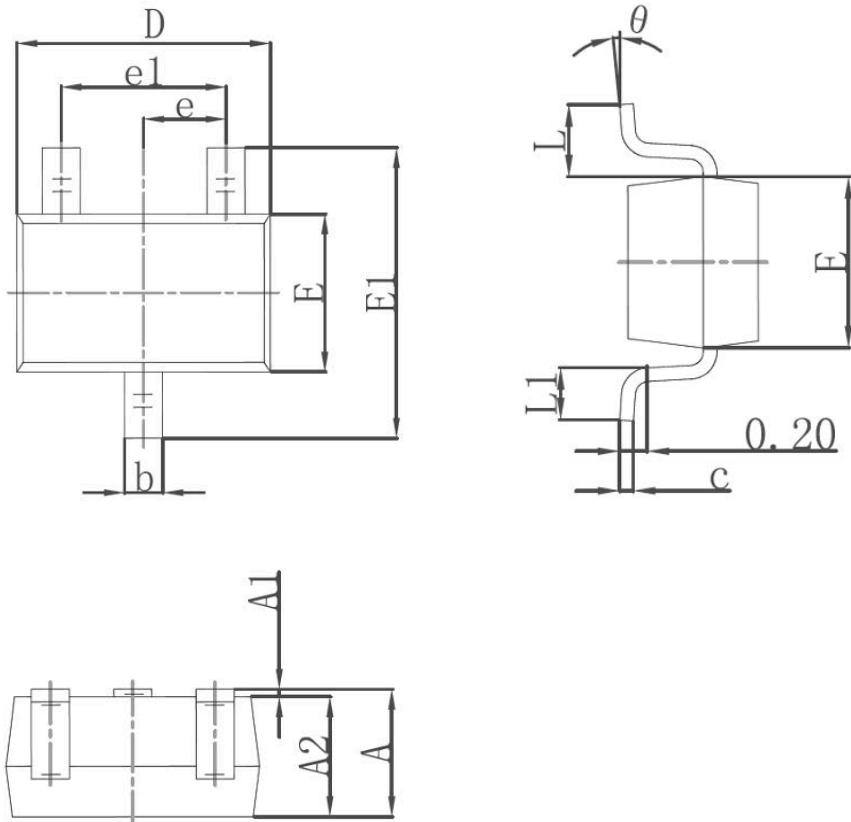


Figure 12. Normalized Transient Impedance

**Package Outline Dimensions SOT-323**



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°